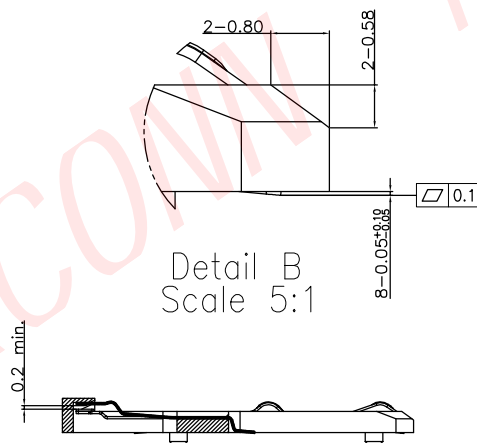
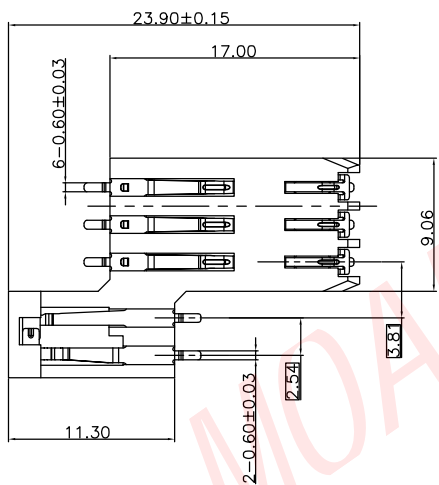
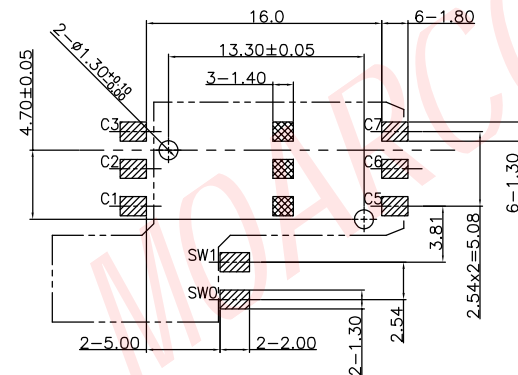


All materials, plating and process meet HF requirements.

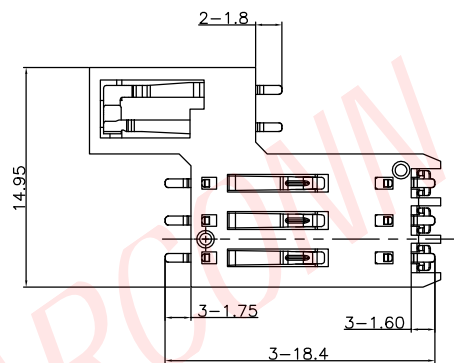
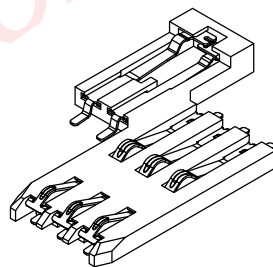
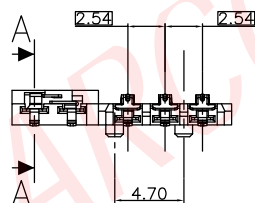
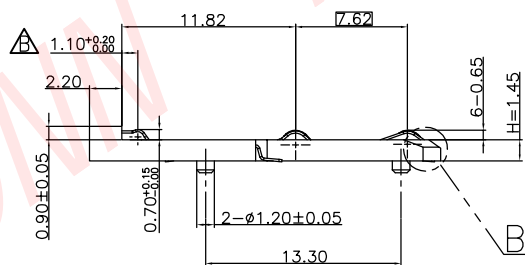


Section A-A



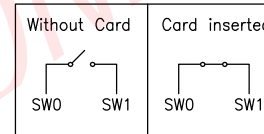
BOARD PAD NO WIRING AREA

Recommended PCB Layout
Gengeral Tolerance : ±0.10mm



NOTE :

- Material:
 - 1-1 Housing: High Temperature Thermoplastic, LCP, Color: Black, UL94V-0
 - 1-2 Terminal and Switch: Phosphor Bronze, T=0.15mm
- Plating:
 - Contact Area: Gold 1μ"
 - Solder Area: Gold Flash.
 - Underplating: Ni overall 80μ" min.
- Specification:
 - 3-1 Contact Current Rating: 0.5A
 - 3-2 Dielectric Withstanding Voltage: AC500V r.m.s.
 - 3-3 Insulation Resistance: 1000 MΩ Minimum, at DC 500V.
 - 3-4 Contact Resistance: 100 mΩ Maximum.
 - 3-5 Mating Cycle: 100,000 Insertions.



B	ECN20200313001	Modify the dimension Δ	Faji	2020.03.13
A	----	NEW RELEASE	janyz	2019.07.12
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

		DONG GUAN MOARCONN ELECTRONIC Co.,Ltd.				
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : Smart card conn. H1.45mm	DRAWING: Faji	DATE: 2020.03.13	
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : SM145-T1200-01	CHECK:	DATE:	DRAWING NO. : D-SM145-T1200-01	APPROVED:	DATE:
		SCALE: 1:1	DWG ID: C D	REV.: B	PAGE: 1 OF 1	